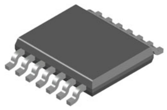
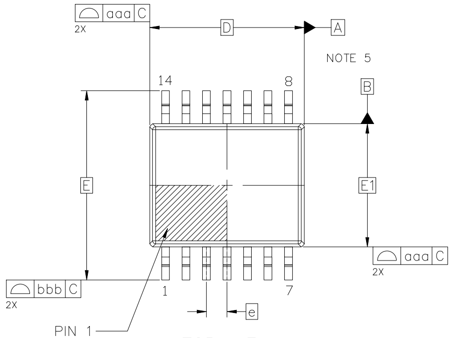


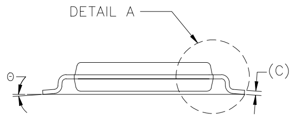
TSSOP14 4.90x3.90x0.95, 0.65P
CASE 948BZ
ISSUE C

DATE 10 JUL 2025

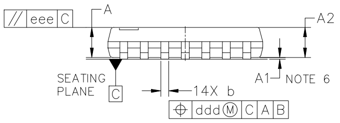
NOTES:
1. DIMENSIONING AND TOLERANCING CONFORM TO ASME Y14.5M, 2018.
2. ALL DIMENSION ARE IN MILLIMETERS (ANGLE IN DEGREES).
3. DIMENSION b DOES NOT INCLUDE DAMBAR PROTRUSION. ALLOWABLE PROTRUSION SHALL BE 0.127 mm IN EXCESS OF MAXIMUM MATERIAL CONDITION.
4. DIMENSIONS D AND E1 DO NOT INCLUDE MOLD FLASH, PROTRUSIONS, OR GATE BURRS. MOLD FLASH, PROTRUSIONS, OR GATE BURRS SHALL NOT EXCEED 0.25mm PER SIDE. DIMENSIONS D AND E1 ARE DETERMINED AT DATUM F.
5. DATUMS A AND B ARE TO BE DETERMINED AT DATUM F.
6. A1 IS DEFINED AS THE VERTICAL DISTANCE FROM THE SEATING PLANE TO THE LOWEST POINT ON THE PACKAGE BODY INCLUDING THE THERMAL ENHANCEMENT ON CAVITY DOWN PACKAGE CONFIGUARATIONS.
7. LEAD THICKNESS (c) AND LEAD WIDTH (b) INCLUDE PLATING THICKNESS.



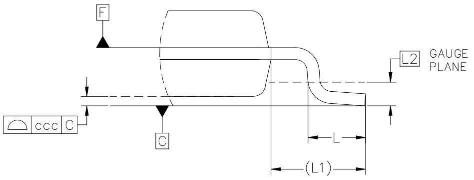
TOP VIEW



END VIEW

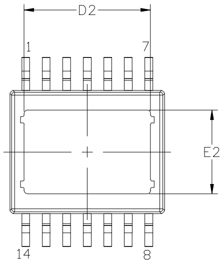


SIDE VIEW

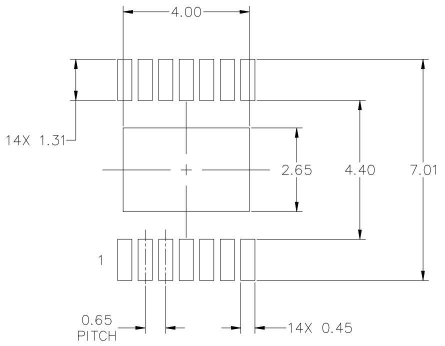


DETAIL A
SCALE 3:1

DIM	MILLIMETERS MIN	NOM	MAX
A	---	---	1.20
A1	0.05	0.10	0.15
A2	0.85	0.95	1.05
b	0.20	0.25	0.30
c		0.20 REF.	
D		4.90 BSC	
D2	3.90	4.00	4.10
E		6.00 BSC	
E1		3.90 BSC	
E2	2.55	2.65	2.75
e		0.65 BSC	
L	0.42	0.52	0.62
L1		1.05 REF.	
L2		0.25 BSC	
Θ	0°	4°	8°
TOLERANCE FOR FEATURE CONTROL FRAME			
aaa		0.10	
bbb		0.20	
ccc		0.08	
ddd		0.10	
eee		0.08	



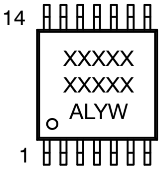
BOTTOM VIEW



RECOMMENDED MOUNTING FOOTPRINT

*For additional information on our Pb−Free strategy and soldering details, please download the onsemi Soldering and Mounting Techniques Reference Manual, SOLDERRM/D.

GENERIC MARKING DIAGRAM*



XXXX = Specific Device Code
A = Assembly Location
L = Wafer Lot
Y = Year
W = Work Week

*This information is generic. Please refer to device data sheet for actual part marking. Pb−Free indicator, “G” or microdot “▪”, may or may not be present. Some products may not follow the Generic Marking.

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DESCRIPTION:	**TSSOP14 4.90x3.90x0.95, 0.65P**	**PAGE 1 OF 1**